

FEATURES

- Low Reverse Recovery Charge
- High Switching Speed
- Low Forward Volt Drop
- Isolated AISiC Base with AlN Substrates
- Dual Diodes can be paralleled for 2400A Rating
- Lead Free Construction

APPLICATIONS

- Chopper Diodes
- Boost and Buck Circuits
- Free-wheel Circuits
- Multi-level Switch Inverters

The DFM1200FXM12-A000 is a dual 1200V, fast recovery diode (FRD) module. Designed for low power loss, the module is suitable for a variety of high voltage applications in motor drives and power conversion.

Fast switching times and low reverse recovery losses allow high frequency operation, making the device suitable for the latest drive designs employing PWM and high frequency switching.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

ORDERING INFORMATION

Order As:

DFM1200FXM12-A000

Note: When ordering, please use the complete part number

KEY PARAMETERS

V_{RRM}		1200V
V_F	(typ)	1.9V
I_F	(max)	1200A
I_{FM}	(max)	2400A

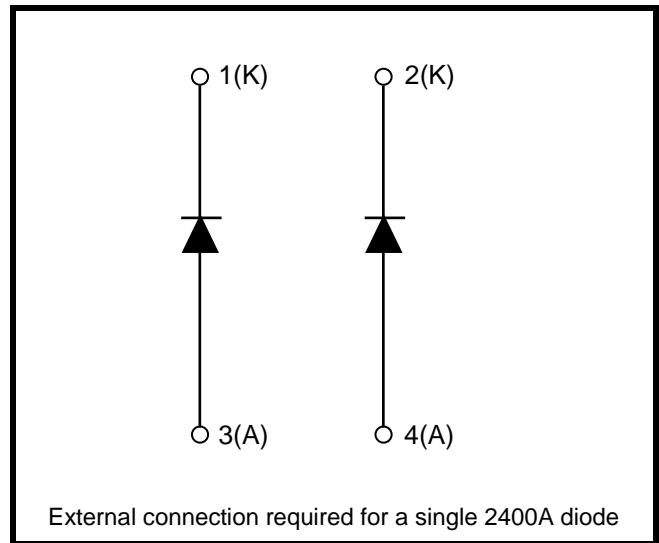


Fig. 1 Circuit configuration

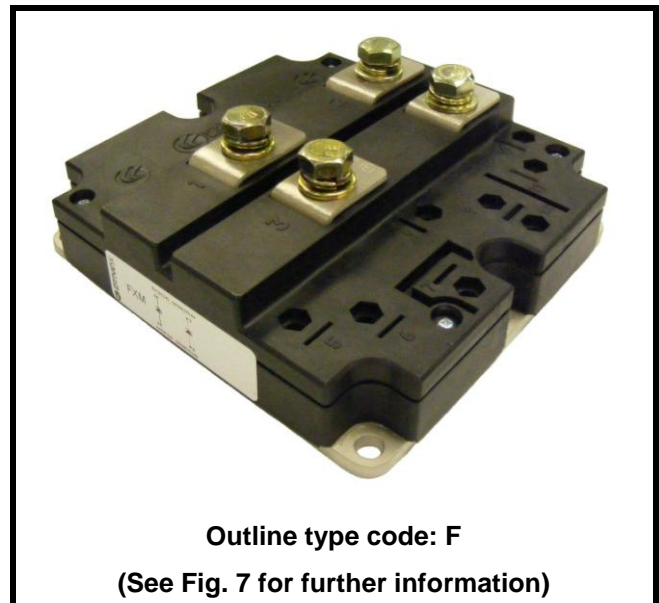


Fig. 2 Package

ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

$T_{\text{case}} = 25^{\circ}\text{C}$ unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
V_{RRM}	Repetitive peak reverse voltage	$T_j = 125^{\circ}\text{C}$	1200	V
I_F	Forward current (per arm)	DC, $T_{\text{case}} = 75^{\circ}\text{C}$, $T_j = 125^{\circ}\text{C}$	1200	A
I_{FM}	Max. forward current	$T_{\text{case}} = 110^{\circ}\text{C}$, $t_p = 1\text{ms}$	2400	A
I^2t	I^2t value fuse current rating	$V_R = 0$, $t_p = 10\text{ms}$, $T_j = 125^{\circ}\text{C}$	400	kA^2s
P_{max}	Max. transistor power dissipation	$T_{\text{case}} = 25^{\circ}\text{C}$, $T_j = 125^{\circ}\text{C}$	5000	W
V_{isol}	Isolation voltage – per module	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	2500	V
Q_{PD}	Partial discharge – per module	IEC1287, $V_1 = 1300\text{V}$, $V_2 = 1000\text{V}$, 50Hz RMS	10	pC

THERMAL AND MECHANICAL RATINGS

Internal insulation material:	AlN
Baseplate material:	AlSiC
Creepage distance:	20mm
Clearance:	10mm
CTI (Comparative Tracking Index):	350

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
$R_{\text{th(j-c)}}$	Thermal resistance (per arm)	Continuous dissipation – junction to case	-	-	20	$^{\circ}\text{C}/\text{kW}$
$R_{\text{th(c-h)}}$	Thermal resistance – case to heatsink (per module)	Mounting torque 5Nm (with mounting grease)	-	-	8	$^{\circ}\text{C}/\text{kW}$
T_j	Junction temperature		-	-	125	$^{\circ}\text{C}$
T_{stg}	Storage temperature range		-40	-	125	$^{\circ}\text{C}$
	Screw Torque	Mounting – M6	-	-	5	Nm
		Electrical connections – M8	-	-	10	Nm

STATIC ELECTRICAL CHARACTERISTICS – PER ARM

$T_{case} = 25^{\circ}C$ unless stated otherwise.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
I_{RM}	Peak reverse current	$V_R = 1200V, T_j = 125^{\circ}C$			30	mA
V_F	Forward voltage	$I_F = 1200A$		1.9	2.2	V
		$I_F = 1200A, T_j = 125^{\circ}C$		2.1	2.4	V
L_M	Inductance			20		nH

STATIC ELECTRICAL CHARACTERISTICS

$T_{case} = 25^{\circ}C$ unless stated otherwise.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
L_M	Module inductance (externally connected in parallel)			15		nH

DYNAMIC ELECTRICAL CHARACTERISTICS – PER ARM

$T_{case} = 25^{\circ}C$ unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
Q_{rr}	Reverse recovery charge	$I_F = 1200A$ $V_R = 600V$ $di_F/dt = 9000A/\mu s$		200		μC
I_{rr}	Peak reverse recovery current			800		A
E_{rec}	Reverse recovery energy			80		mJ

$T_{case} = 125^{\circ}C$ unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
Q_{rr}	Reverse recovery charge	$I_F = 1200A$ $V_R = 600V$ $di_F/dt = 8400A/\mu s$		300		μC
I_{rr}	Peak reverse recovery current			920		A
E_{rec}	Reverse recovery energy			140		mJ

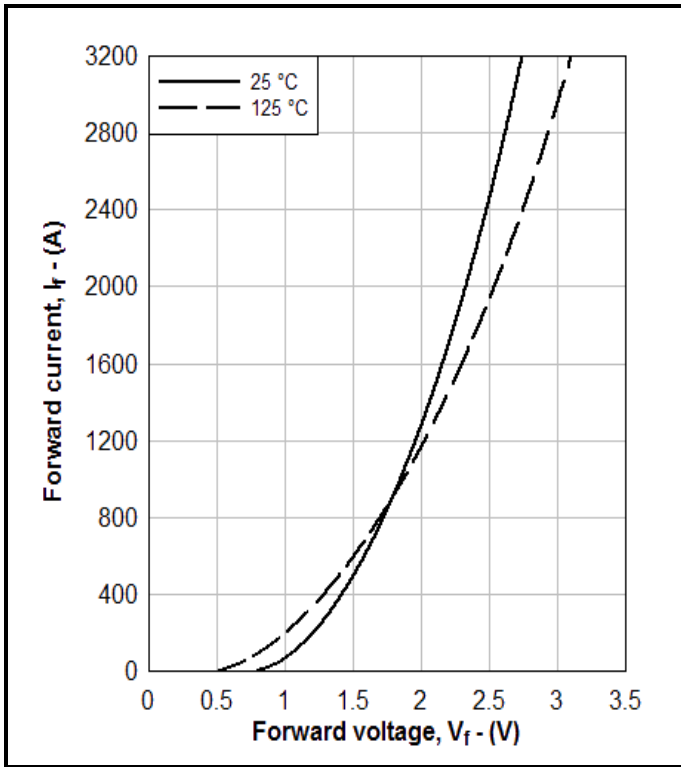


Fig. 3 Diode typical forward characteristics

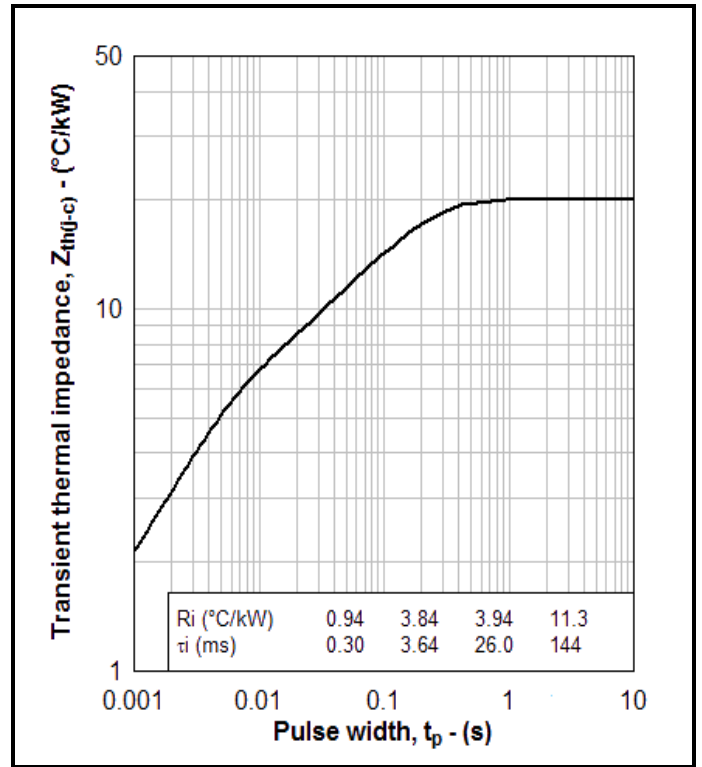


Fig. 4 Transient thermal impedance

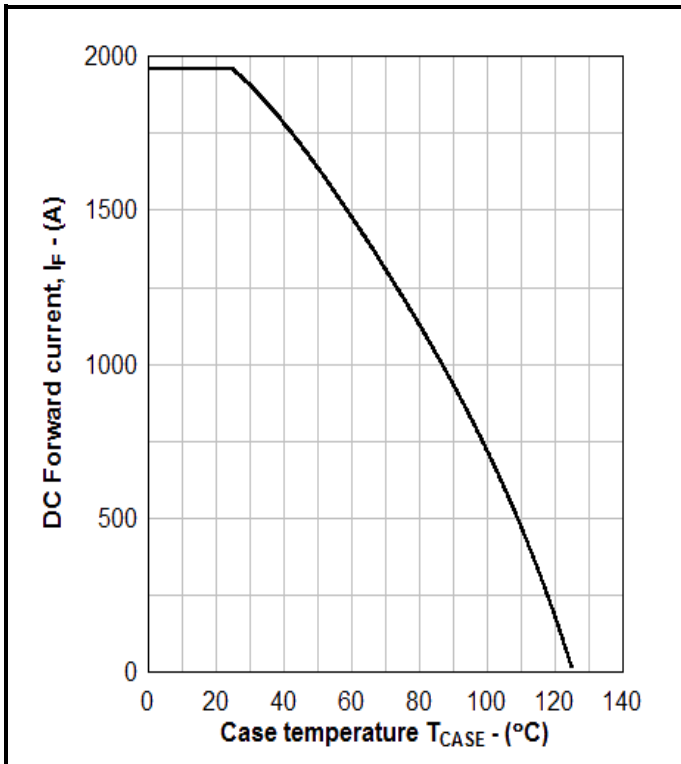


Fig. 5 DC Current rating vs case temperature

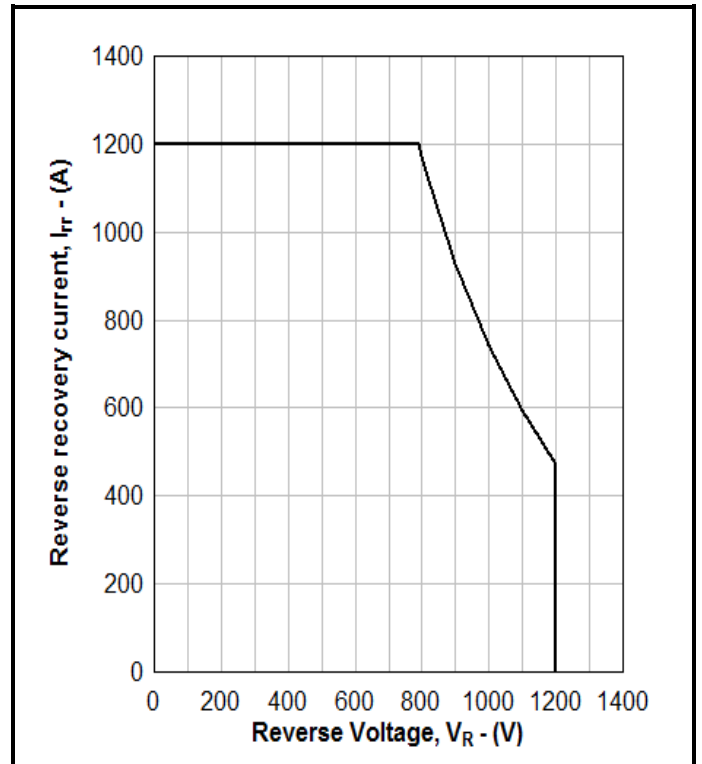
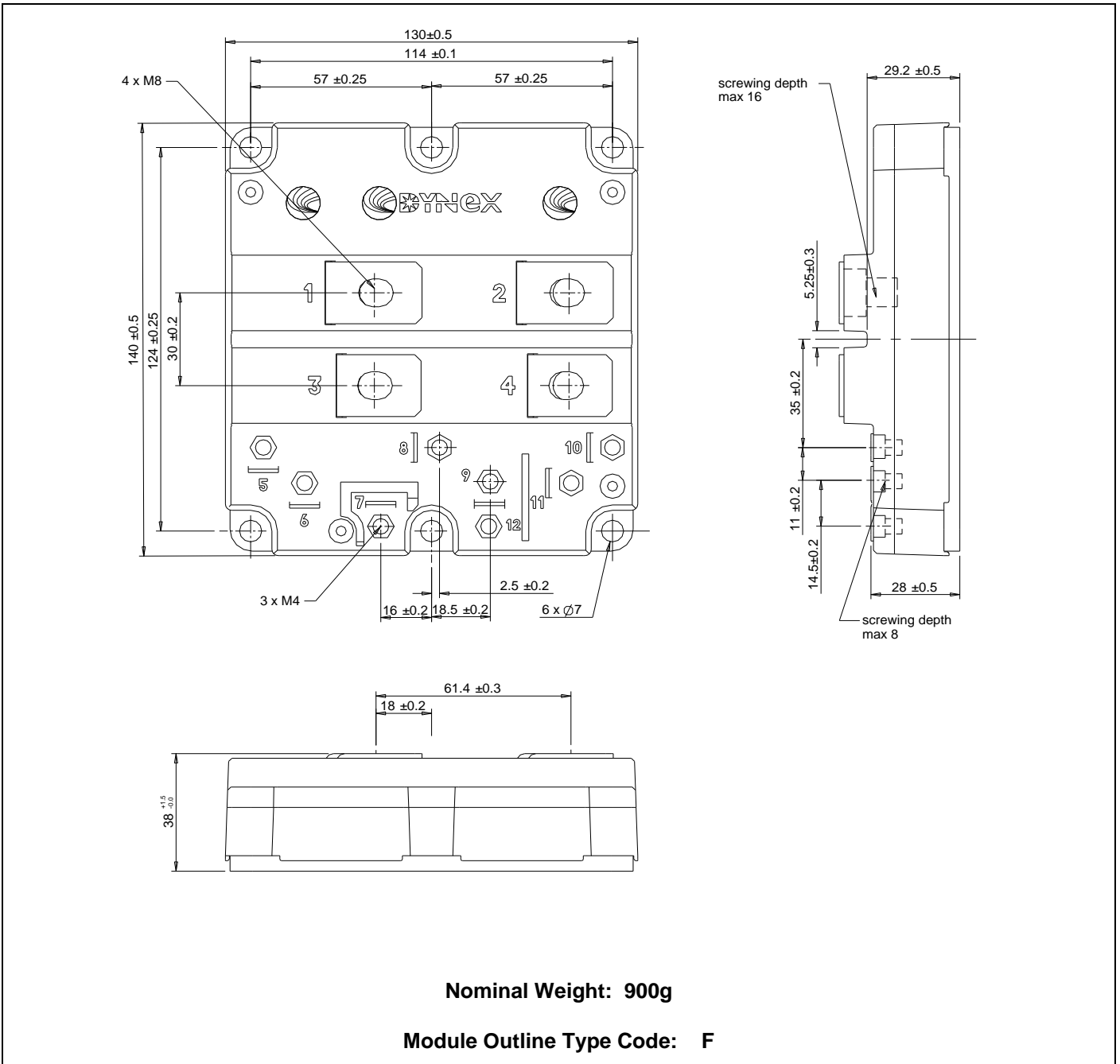


Fig. 6 RBSOA

PACKAGE DETAILS

For further package information, please visit our website or contact Customer Services.
 All dimensions in mm, unless stated otherwise.
DO NOT SCALE.



Nominal Weight: 900g

Module Outline Type Code: F

Fig. 7 Module outline drawing

HEADQUARTERS OPERATIONS**DYNEX SEMICONDUCTOR LTD**

Doddington Road, Lincoln
Lincolnshire, LN6 3LF, United Kingdom

Fax: +44(0)1522 500550

Tel: +44(0)1522 500500

CUSTOMER SERVICE**DYNEX SEMICONDUCTOR LTD**

Doddington Road, Lincoln
Lincolnshire, LN6 3LF, United Kingdom

Fax: +44(0)1522 500020

Tel: +44(0)1522 502901 / 502753

email: power_solutions@dynexsemi.com

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